

# **CUSTOMER ADVISORY**

## **GLASS SEAL PGA**

### **Overview**

In 1993 Altera converted its 68-, 84-, and 100-pin solder-seal Pin Grid Array (PGA) packages to a glass-sealed PGA package. However, since Altera acquired the Intel product line in 1994 the company has been supporting orders for the solder seal PGA package. Going forward, Altera will be converting to the glass seal PGA package. The glass seal PGA package continues to meet MIL-STD-883, Method 5005 Group D qualification standards.

### **Description of Changes**

The glass-sealed package is composed of two piece parts: a bare-cavity ceramic base and a ceramic lid with a UV transparent, quartz window that sits flush with the top of the base. The ceramic lid replaces the existing windowed kovar lid on Intel solder seal packages.

The die attach method and material, silver glass, is the same as that used for all of Altera's ceramic quad flat pack packages. Material with backside date codes equal to or greater than 9626 indicate a glass-sealed PGA (e.g. 9626C).

Should you need additional information or assistance to qualify the change described, please contact your local sales representative.